

AMENDMENTS TO THE CLAIMS

1.(Currently amended) A blade-like connecting needle for measuring a semiconductor wafer, comprising:

a blade signal line for transmitting signal from the semiconductor wafer,

a support insulator covering ~~at least a portion~~ an entire outer circumference of said blade signal line,

a plurality of blade guard patterns disposed ~~in or on~~ at least on a portion of a surface of said support insulator for electromagnetically shielding said blade signal line, and

a probe supported by said support insulator and connected to said blade signal line.

2.(Original) A blade-like connecting needle according to claim 1, wherein at least a portion of said probe is covered with an insulating material.

3.(Original) A blade-like connecting needle according to claim 1, further comprising a connector for connecting said blade signal line to an external circuit.

4.(Original) A blade-like connecting needle according to claim 3, wherein said connector includes in at least a portion thereof a signal line covered with an insulating material.

5. (Canceled)

6.(Currently amended) A blade-like connecting needle according to claim 1, wherein the ~~blade-like~~linelike connecting needle is connected to a probe card including a shielded electric conductive path.

7-9. (Canceled)